CC1350 RF

VDD Decoupling Capacitors

Place L1 and C8 close to pin 33

R67, R68, R69 select source of power for RF switch; only mount one of them

Sub-1 GHz RF section

2.4 GHz RF section

C24 and C59 for antenna matching
XDS110 Debugger Interface

P10 selects the voltage source for the level shifters.
When powering CC1350 from the XDS supply, connect jumper between pins 1 and 2.
When powering CC1350 from the external supply, connect jumper between pins 2 and 3.

Jumpers M12 to be mounted between pins 1 and 2 on P10

Jumpers M1–M11 to be mounted on header P4

Use P5 for debugging CC1350 with an external debugger (requires that all jumpers on P4 be removed)

Use P7 for debugging external targets (requires that all jumpers on P4 be removed)

XDS-RST = 0 → output = 0
XDS-RST = 1 → output = Hi-Z
TMS signal is bidirectional. TMS_DIR used to control direction of level shifter

DIR = H: A → B
DIR = L: B → A
OE = H: output = Hi-Z

Title: LAUNCHXL-CC1350
Drawn: TER, KHT
Checked: NN
Size: A3
Rev: 1.1.1
Sheet: 3 of 4
Date: Monday, April 11, 2016
XDS110 Debugger

XDS_VCC = 3.3 V
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